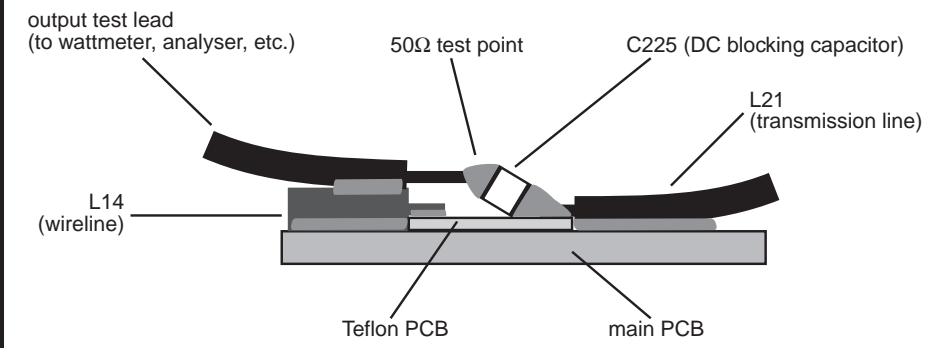


Q1 & Q2 Output Test Lead

Desolder C225 and resolder on edge as shown.
 Remove the wireline clamping plate and solder the test lead outer core to the outer core of the wireline (L14 shown).
 Solder the inner core of the test lead to the raised end of C225.



To test Q1 & Q2, provide 2.5-3W drive power to Q1 through the input test lead. While testing, ensure that the output test lead on Q2 is terminated at all times into a good 50Ω RF load.

Q1-Q6 Output Test Lead (Q4 Shown)

Refer to drawing B above.
 Desolder the appropriate DC blocking capacitor and resolder on edge.
 Remove the wireline clamping plate and solder the test lead outer core to the outer core of the wireline.
 Solder the inner core of the test lead to the raised end of the DC blocking capacitor.
 To test, drive the transistor with approximately 10W over the 850-870Mhz frequency range and expect a minimum output of 30W.

Q1-Q6 Input Test Lead (Q4 Shown)

Desolder the inner core of the appropriate transmission line and lift it off its pad.
 Solder the test lead outer core to the transmission line outer core.
 Solder the inner cores of the transmission line and the test lead together off the surface of the PCB.

Q1 & Q2 Input Test Lead

Desolder the inner core of L16 and lift it off its pad.
 Solder the test lead outer core to the pad provided on the earth plane.
 Solder the inner cores of L16 and the test lead together off the surface of the PCB.

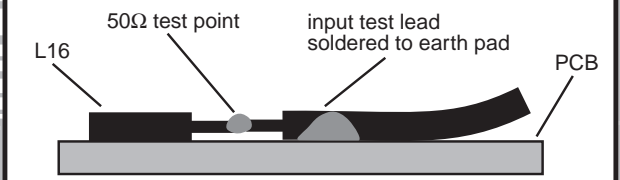


Figure 4.1 T889 Test Break Point Location